

Title (en)
RADIATION-SENSITIVE RESIN COMPOSITION

Title (de)
LICHTEMPFLINDLICHE HARZ-ZUSAMMENSETZUNG

Title (fr)
COMPOSITION RESINEUSE RADIOSENSIBLE

Publication
EP 1046955 A1 20001025 (EN)

Application
EP 99947958 A 19991019

Priority
• JP 9905750 W 19991019
• JP 29871098 A 19981020

Abstract (en)
A good heat-resistant radiation-sensitive resin composition containing an alkali-soluble resin obtained by condensation, with phenols as necessary, of methylolated bisphenols represented by following general formula, a cross-linking agent and a photosensitizer. <CHEM> wherein R1 to R4 each represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or -CH₂OH, whereupon at least one of R1 to R4 represents -CH₂OH, and R5 and R6 each represents a hydrogen atom or an alkyl group having 1 to 3 carbon atoms.
A radiation sensitive resin composition comprises an alkali-soluble resin prepared by condensation of a methylol-bisphenol compound alone or with a phenol, a crosslinkable agent and an acid generator has excellent heat-resistance.. The methylol bisphenol compound is of formula (I). [Image] R 1 - R 4H, 1 - 3C alkyl or CH 2OH and at least one of these is CH 2OH; R 5, R 6H or 1-3C alkyl.

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G03F 7/023

IPC 8 full level
C08G 8/06 (2006.01); **C08G 8/20** (2006.01); **C08G 8/24** (2006.01); **G03F 7/023** (2006.01); **G03F 7/038** (2006.01); **H01L 21/027** (2006.01)

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